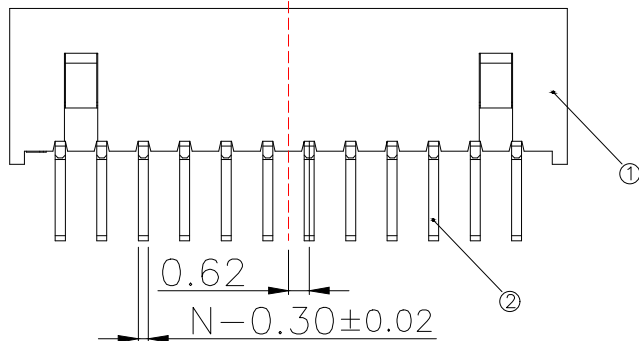
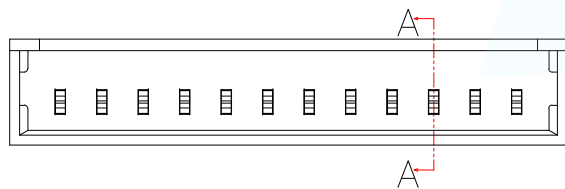
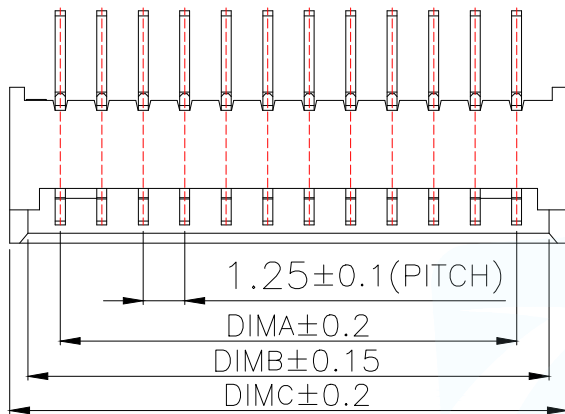


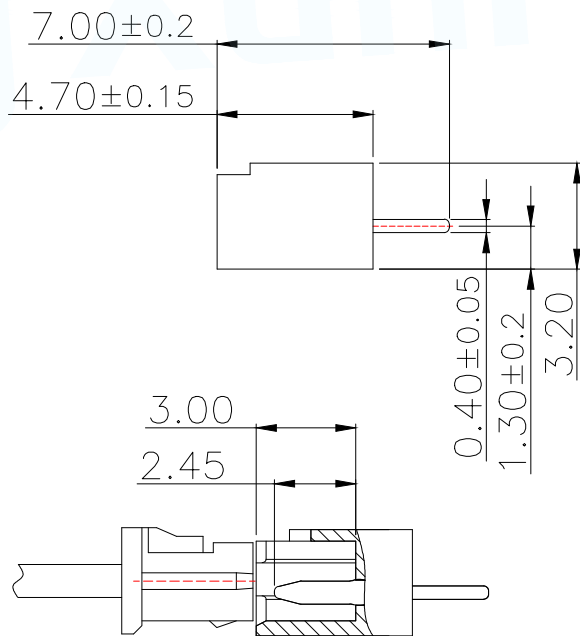
LOCK CONFIGURATION (锁扣位置)



| 序号 | 品名 | 材质 |
|----|--|------------------------------|
| 1 | 1.25 Pitch S/T Wire To Board Housing DIP(H=4.7) | PA66 UL94V-2 Yellow |
| 2 | 1.25 Pitch S/T Wire To Board Terminal DIP(H=4.7) | Copper Alloy/ Tin Plating |

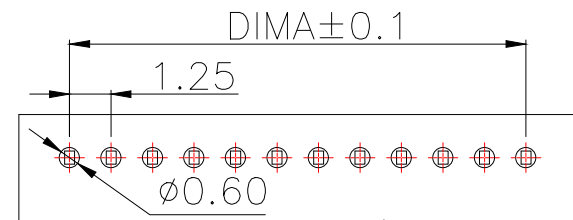
Technical Index:

- 1.The surface of the plastic parts should be smooth,no rough edges,no obvious shrinkage,defects,cracks and other phenomena)
- 2.Lock Configuration: 2 to 3Pin is 1, ≥ 4Pin is 2
- 3.Temperature range: -25°C~+85°C.
- 4.Rated voltage: 125V, AC/DC.
- 5.Contact resistance: ≤0.02Ω.
- 6.Insulation resistance: ≥100MΩ



SECTION A-A

| Part No | Pin | A | B | C |
|------------------------|-----|-------|-------|-------|
| WAFER-MX1.25-2PZZ-H62 | 2 | 1.25 | 3.20 | 4.30 |
| WAFER-MX1.25-3PZZ-H62 | 3 | 2.50 | 4.45 | 5.55 |
| WAFER-MX1.25-4PZZ-H62 | 4 | 3.75 | 5.70 | 6.80 |
| WAFER-MX1.25-5PZZ-H62 | 5 | 5.00 | 6.95 | 8.05 |
| WAFER-MX1.25-6PZZ-H62 | 6 | 6.25 | 8.20 | 9.30 |
| WAFER-MX1.25-7PZZ-H62 | 7 | 7.50 | 9.45 | 10.55 |
| WAFER-MX1.25-8PZZ-H62 | 8 | 8.75 | 10.70 | 11.80 |
| WAFER-MX1.25-9PZZ-H62 | 9 | 10.00 | 11.95 | 13.05 |
| WAFER-MX1.25-10PZZ-H62 | 10 | 11.25 | 13.20 | 14.30 |
| WAFER-MX1.25-11PZZ-H62 | 11 | 12.50 | 14.45 | 15.55 |
| WAFER-MX1.25-12PZZ-H62 | 12 | 13.75 | 15.70 | 16.80 |
| WAFER-MX1.25-13PZZ-H62 | 13 | 15.00 | 16.95 | 18.05 |
| WAFER-MX1.25-14PZZ-H62 | 14 | 16.25 | 18.20 | 19.30 |
| WAFER-MX1.25-15PZZ-H62 | 15 | 17.50 | 19.45 | 20.55 |
| WAFER-MX1.25-16PZZ-H62 | 16 | 18.75 | 20.70 | 21.80 |
| WAFER-MX1.25-17PZZ-H62 | 17 | 20.00 | 21.95 | 23.05 |
| WAFER-MX1.25-18PZZ-H62 | 18 | 21.25 | 23.20 | 24.30 |
| WAFER-MX1.25-19PZZ-H62 | 19 | 22.50 | 24.45 | 25.55 |
| WAFER-MX1.25-20PZZ-H62 | 20 | 23.75 | 25.70 | 26.80 |



适用线路板(PCB LAYOUT)

| | | | | |
|---------------------------------------|-------------|-----------|---|-----------------------|
| MANUFACTURE DWG | | | 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd | |
| UNLESS OTHERWISE SPECIFIED TOLERANCES | | | TITLE:1.25 PITCH H4.7 S/T WIRE TO BOARD DIP CONN. | |
| DECIMALS: | ANGLES: | | PAR | WAFER-MX1.25-NPZZ-H62 |
| X.:±0.50 | X':.:±5° | | DWN | |
| .X:±0.20 | X.X':.:±3° | CHKD | | |
| .XX:±0.10 | X.XX':.:±1° | APVD | | |
| CUSTOMER COPY | | SCALE:1:1 | UNIT:MM | |
| | | SIZE:A4 | SHEET:1F1 | REV:A |